



Final Product Change Notification

201510005F01U01

Issue Date: 07-Mar-2016

Effective Date: 05-Jun-2016

UPDATE

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QUALITY

Change Category

<input checked="" type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

Release of 8 inch wafer diameter for product family BAS516 in SOD523 package

Details of this Change

Editorial update of PCN 201510005F01.

In addition to the announcement of the 8 inch wafer diameter release, the top metallization thickness of the affected switching diodes will be adapted.

This update is to inform about the unpublished announcement of the revised top side metallization thickness.

Old products: Production using 6 inch wafer diameter, top side metallisation thickness 1.4µm

Changed products: Production using 6 and 8 inch wafer diameter, top side metallisation thickness 1.5µm (8 inch wafers)

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Text of the original PCN:

Release of production using 8 inch wafer diameter for product family BAS516 in SOD523 (SC-79) package.

Old products: Production using 6 inch wafer diameter

Changed products: Production using 6 and 8 inch wafer diameter

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Why do we Implement this Change

To increase flexibility and volume ramp-up.

Identification of Affected Products

The 8 inch products can be identified by a marker on the die surface.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 06-Jun-2016

Update Information

Editorial update of the revised top side metallization thickness.

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Supply using 6 inch wafer will be continued.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 06-Apr-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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Changed Orderable Part#

BAS516,135

BAS516,115

